



Device Material Content

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December, 2017

Package: 44 PLCC
Total Device Weight 2.180 Grams

Package Code:

JN

Products:

M4A

Assembly: ASEM
Size (mm): 16.5 x 16.5mm
Lead pitch (mm): 1.27
MSL: 3
Reflow max (°C): 245

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	0.53%	0.0116			Silicon chip	7440-21-3	100.00%	Die size: 3.5 x 2.8 mm
Mold Compound	84.69%	1.8462	6.35% 2.54% 58.39% 16.94% 0.47%	0.1385 0.0554 1.2730 0.3692 0.0102	Epoxy Resin Phenol Resin Silica (Amorphous) A Silica (Amorphous) B Carbon Black	- - 60676-86-0 7631-86-9 1333-86-4	7.50% 3.00% 68.95% 20.00% 0.55%	Mold Compound: Sumitomo G630 series
D/A Epoxy	0.05%	0.0011	0.04% 0.00% 0.00% 0.01% 0.00%	0.00082 0.00008 0.00002 0.00011 0.00005	Silver Epoxy Acylate Substituted Polyamine Bisphenol F 2-Ethylhexyl Glycidyl Ether	7440-22-4 15625-89-5 68490-66-4 28064-14-4 2461-15-6	75.50% 7.50% 2.00% 10.00% 5.00%	Die attach: Yizbond 8143
Wire	0.09%	0.0020	0.09%	0.0020	Gold (Au)	7440-57-5	100.00%	1.00 mil diameter; 1 wire per package lead
Plating	0.46%	0.0100	0.46%	0.0100	Tin (Sn)	7440-31-5	100.00%	Plating is 100% Matte Sn; thickness is >10.2µm
Leadframe	14.18%	0.3091	13.97% 0.11% 0.11%	0.3045 0.0023 0.0023	Copper (Cu) Aluminum (Al) Manganese (Mg)	7440-50-8 7429-90-5 7439-96-5	98.50% 0.75% 0.75%	C151

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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